PK132 (v4.0) December 23, 2011

100% Material Declaration Data Sheet VOG48

Pure Tin Leads*

*Xilinx Platform Flash PROM VOG48 with datecode prior to 1030 will have Matte Tin (Sn) Lead-frame plating finish

Average Weight: 0.520 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon die					**0.003864**	**0.743%**
	Silicon	7440-21-3	99.70		0.003850	
	Aluminium (Al)	7429-90-5	0.20		0.000010	
	Copper (Cu)	7440-50-8	0.05		0.000002	
	Titanium	7440-32-6	0.05		0.000002	
Lead-frame alloy					**0.109060**	**20.973%**
	Copper (Cu)	7440-50-8	97.25		0.106060	
	Iron (Fe)	7439-89-6	2.35		0.002560	
	Zinc (Zn)	7440-66-6	0.12		0.000130	
	Iron Phosphide (FeP)	26508-33-8	0.08		0.000090	
	Silver (Ag)	7440-22-4	0.20		0.000220	
Lead-frame plating					**0.003140**	**0.604%**
	Tin (Sn)	7440-31-5	100.00		0.003140	
Die Attach Material					**0.000760**	**0.146%**
	Silver	7440-22-4	79.00		0.000600	
	Bismaleimide and acrylate polymer	Trade Secret	14.00		0.000110	
	Acrylate monomer	Trade Secret	7.00		0.000050	
Gold Wire					**0.000670**	**0.129%**
	Gold	7440-57-5	100.00		0.000670	
Mold Compound Encapsulation					**0.402500**	**77.404%**
	Epoxy Resin	Trade Secret	8.00		0.032200	
	Phenol Resin	Trade Secret	8.00		0.032000	
	Silicon Dioxide	60676-86-0	83.50		0.336090	
	Carbon Black	1333-86-4	0.50		0.002010	

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NiPdAu Leads**

** Xilinx Platform Flash PROM VOG48 with datecode 1030 or after will have NiPdAu Lead-frame plating finish

Average Weight: 0.520 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon die					**0.003864**	**0.743%**
	Silicon	7440-21-3	99.70		0.003850	
	Aluminium (Al)	7429-90-5	0.20		0.000010	
	Copper (Cu)	7440-50-8	0.05		0.000002	
	Titanium	7440-32-6	0.05		0.000002	
Lead-frame alloy					**0.109820**	**21.119%**
	Copper (Cu)	7440-50-8	97.25		0.106800	
	Iron (Fe)	7439-89-6	2.35		0.002580	
	Zinc (Zn)	7440-66-6	0.12		0.000130	
	Iron Phosphide (FeP)	26508-33-8	0.08		0.000090	
	Silver (Ag)	7440-22-4	0.20		0.000220	
Lead-frame plating					**0.002390**	**0.460%**
	Nickel (Ni)	7440-02-0	91.70		0.002190	
	Palladium (Pd)	7440-05-03	5.85		0.000140	
	Gold (Au)	7440-57-5	2.45		0.000060	
Die Attach Material					**0.000760**	**0.146%**
	Silver	7440-22-4	79.00		0.000600	
	Bismaleimide and acrylate polymer	Trade Secret	14.00		0.000110	
	Acrylate monomer	Trade Secret	7.00		0.000050	
Gold Wire					**0.000670**	**0.129%**
	Gold	7440-57-5	100.00		0.000670	
Mold Compound Encapsulation					**0.402500**	**77.404%**
	Epoxy Resin	Trade Secret	8.00		0.032200	
	Phenol Resin	Trade Secret	8.00		0.032000	
	Silicon Dioxide	60676-86-0	83.50		0.336090	
	Carbon Black	1333-86-4	0.50		0.002010	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
3/21/06	1.0	Initial Xilinx release.
7/10/06	1.1	100% Material Declaration
9/29/06	1.2	Updated component descriptions
12/10/07	2.0	Material content change per XCN07015
03/18/11	3.0	Material content change per XCN9026
12/23/11	4.0	Datecode change

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